ABSTRACT OF THE DISCLOSURE

A surface acoustic wave device is constructed and manufactured by a flip chip method, such that stress produced due to a temperature change in the bonded portion between a surface acoustic wave element and an electronic component package is minimized. The surface acoustic wave device includes a piezoelectric substrate bonded to the electronic component package via metal bumps, wherein the piezoelectric substrate has a substantially rectangular bonding surface on which the metal bumps are provided, and has different linear thermal expansion coefficients along the directions of two sides of the bonded surface, and the maximum distance between the metal bumps arranged in one of the two side directions in which there the piezoelectric substrate and the package have a greater difference between the linear thermal expansion coefficients is less than the maximum distance between the metal bumps arranged in the other side direction in which the piezoelectric substrate and the package have a smaller difference between the linear thermal expansion coefficients.